



100% Material Declaration Data Sheet PCG84

PK117 (v1.2) September 28, 2006

Material Declaration Data Sheet

Average Weight: 7.248 g

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
Silicon Die					0.02369	0.33%
	Silicon		100%		0.023688	
Die Attach Material					0.00377	0.05%
	Resin	Trade Secret	7.00		0.000264	
	Silver	7440-22-4	70.00		0.002640	
	Zirconium	Trade Secret	0.10		0.001252	
	Mixed aryl allyl glycidyl compounds	Trade Secret	3.00		0.000113	
	Amine	Trade Secret	5.00		0.000189	
	Gamma Butyrolactone	Trade Secret	5.00		0.000189	
	Diglycidylether of bisphenol-F	Trade Secret	10.00		0.000377	
Mold Compound					5.91943	81.67%
	Epoxy Resin (EP)	Trade Secret	7.50		0.443957	
	Silica	60676-86-0	86.00		5.090706	
	Carbon Black	1333-86-4	0.50		0.029597	
	Epoxy Cresol Novolac	Trade Secret	2.00		0.118389	
	Phenolic Resin	Trade Secret	4.00		0.23677	
Leadframe					1.25241	17.28%
	Copper	7440-50-8	99.90		1.251153	
	Zirconium	7440-67-7	0.10		0.001252	
Leadframe Plating					0.00254	0.04%
	Silver	7440-22-4	100.00		0.002544	
Bond Wire					0.00348	0.05%
	Gold	7440-57-5	99.99		0.003483	
	Silver	7440-22-4	0.0005			
	Copper	7440-50-8	0.0022			
Ext. Plating					0.04241	0.58%
	Tin	7440-31-5	100.00		0.042406	

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Revision History

The following table shows the revision history for this document.

Date	Revision	Revision
3/08/06	1.0	Initial release.
7/05/06	1.1	100% Material Declaration.
9/28/06	1.2	Updated component descriptions.